Serial Number: 10/612,328

Dkt: 884.946US1 (INTEL)

Filing Date: June 30, 2003
Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND

MICROELECTRONIC PACKAGE APPLICATION

Assignee: Intel Corporation

## **REMARKS**

This responds to the Office Action mailed on March 30, 2005.

Claims 1, 13, and 16 are amended and claim 17 is canceled; as a result, claims 1-16, 18-20, and 24-25 are now pending in this application.

## **Double Patenting Rejection**

Claim 16 was provisionally rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 21 and 22 of copending Application No. 10/071,743.

The Applicant reserves the right to take action regarding this matter in the future.

## §102 Rejection of the Claims

Claims 1-20 and 24-25 were rejected under 35 USC § 102(e) as being anticipated by Jayaraman et al. (U.S. 2003/0153667). The Examiner maintains that FIGs. 1 and 4 show fusible 403 and non-fusible 402 particles wherein "non-fusible particles dispersed within the polymer matrix, wherein the fusible particles have a mean particle size that is greater than the maximum particle size of the non-fusible particles when fusible particles and non-fusible particles are blended together in the polymer matrix" as is claimed. However, the FIGs. Clearly show a contrary feature. The fusible particles 403 in FIG. 4A and FIG.1 are much smaller than the non-fusible particles 402 when the fusible and non-fusible particles are blended together in the polymer matrix. This is contrary to what is claimed which is that the fusible particles have a mean particle size that is greater than the maximum particle size of the non-fusible particles when fusible particles and non-fusible particles are blended together in the polymer matrix"

AMENDMENT UNDER 37 C.F.R. 1.116 - EXPEDITED PROCEDURE

Page 6 Dkt: 884.946US1 (INTEL)

Serial Number: 10/612,328 Filing Date: June 30, 2003

Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND

MICROELECTRONIC PACKAGE APPLICATION

Assignee: Intel Corporation

## Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 373-6976 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

JAMES C MATAYABAS ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. Attorneys for Intel Corporation P.O. Box 2938 Minneapolis, Minnesota 55402

(612) 373-6976

Reg. No. 37,650

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 29th day of April, 2005.

Name